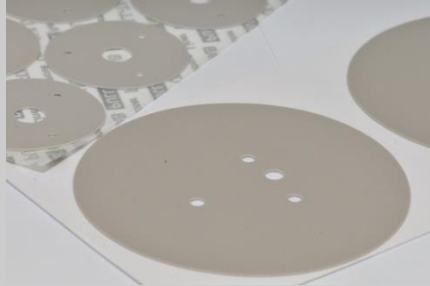


## THERMALLY CONDUCTIVE GAP FILLER 3.0W/m-K

### Features and Benefits

- 3.0W/m-K thermal conductivity
- Moderate compressibility
- Cost effective
- Electrically isolating



### Typical Applications

- Cooling component to the chassis, frame, or other type of heat spreader
- Mass storage device
- Heat pipe assemblies
- RDRAM memory modules
- Motor control
- Telecommunication hardware

### Optional Configurations

- Fibreglass reinforcements are recommended for  $\leq 0.03"$
- Adhesive coatings are optional
- Aluminium lamination is optional
- Can be die-cut into specific dimensions

E-Fill 8100 Spec 05 is a surface-tack and thermal performance improved derivative of the original E-Fill 8100 gap pad. This special feature is benefited from a revised metal oxide filler matrix. It is electrically non-conductive and conforms to UL94 V0 standard.

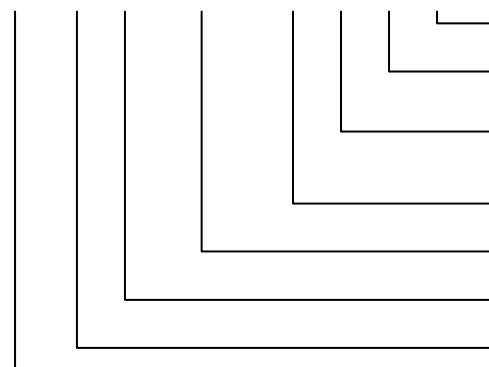
Typical Properties	E-Fill 8100 Spec 05	Test Method
Construction & Composition	Soft silicone elastomer	—
Color	Grey	Visual
Thickness Range /inch (mm)	0.012"~0.30" (0.3~7.62)	—
Standard Sheet Size	12" x 16"	—
Density /g.cm <sup>-3</sup>	3.10	—
Hardness /Shore 00	60	ASTM D2240
UL Flammability Rating	UL94 V0	—
Temperature Range /°C	-40~200°C	—
Thermal Conductivity W.m <sup>-1</sup> .K <sup>-1</sup>	3.0	ASTM D5470 (modified)
Breakdown Voltage /V	>5000	ASTM D149
Shelf Life	24 months	—

Please contact us for other special requirements

Carrier Treatment	Criteria
Fiber Glass (FG)	Compulsory for $\leq 0.012"$ (0.3mm)
Rubberized Cloth (RC)	Not Recommended
Pressure Sensitive Adhesive (PSA)	Not Recommended
Detachable Adhesive (DA)	Not Recommended
Aluminum Foil (AL)	Not Recommended
Kapton (PI)	Not Recommended
Talc treatment (DAT)	Not Recommended

### Product Code and Descriptions

E-Fill 81 XX Spec 05 -XX -XX -XX -XX



**Dimensions**  
SS = Standard sheet size

**Release Liner**  
ST = Standard  
OT = Other

**PSA**  
A1 = One side  
A2 = Both sides  
OT = Other

**Carrier**  
FG = Fiberglass  
RC = Rubberized Cloth  
CB = Combination  
OT = Other

**Spec 05 = Special Derivative #**

**Thickness (mil)**  
00 = Custom thickness  
40 = 40mil

**81 = 8100 Series**  
E-Fill = E-Fill gap filling material

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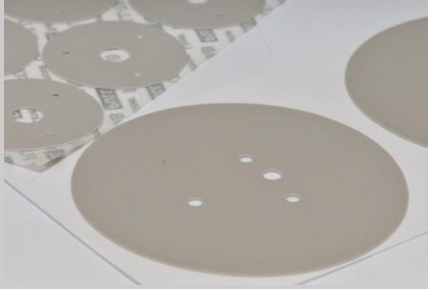
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## 产品特点

- 导热率 3.0W/m-K
- 中等压缩比
- 低成本
- 电绝缘



## 一般应用

- 高速大容量存储设备
- RDRAM 记忆模组
- 热管组件
- 底盘，框架或其他散热组件
- 电机控制器
- 无线通信硬件

## 其他配置

- 产品厚度 ≤ 0.03", 建议使用玻璃纤维强化
- 可选择胶粘剂涂层
- 可选择铝箔强化
- 可模切成特定尺寸

E-Fill 8100 Spec 05 是基于 E-Fill 8100 改良而成的。

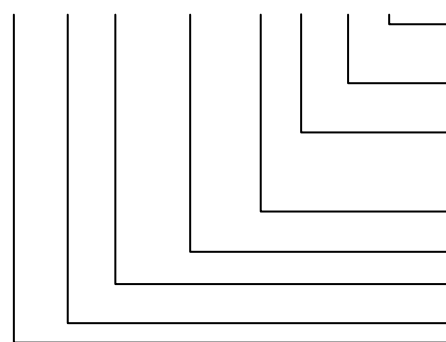
新的填充物料配方使 E-Fill 8100 Spec 05 的表面粘性及导热性能得到大幅的提升。E-Fill 8100 Spec 05 是电绝缘体而且达到 UL94V0 防火要求。

一般特性	E-Fill 8100 Spec 05	测试方法
结构及主要成分	硅树脂弹性体	—
颜色	灰色	目测
厚度 /inch (mm)	0.012"~0.30" (0.3~7.62)	—
标准片材尺寸	12" x 16"	—
密度 /g.cm <sup>-3</sup>	3.10	—
硬度 /Shore 00	60	ASTM D2240
UL 燃烧等级	UL94 V0	—
使用温度 /°C	-40~200°C	—
导热率 W.m <sup>-1</sup> .K <sup>-1</sup>	3.0	ASTM D5470 (modified)
击穿电压/V	>5000	ASTM D149
有效期/Months	24	—
如对产品有特殊要求，请联络我们		

载体	标准
玻璃纤维 (FG)	厚度 ≤ 0.012" (0.3mm) 必须使用
胶布 (RC)	不建议使用
压敏胶 (PSA)	不建议使用
不粘胶 (DA)	不建议使用
铝箔 (AL)	不建议使用
聚酰亚胺膜 (PI)	不建议使用
滑石粉处理 (DAT)	不建议使用

## 产品编码及描述

E-Fill 81 XX Spec 05 XX XX XX XX



**尺寸**  
 SS = 标准尺寸  
 CD = 定制尺寸  
**高型膜**  
 ST = 标准  
 OT = 其他  
**压敏胶**  
 A1 = 单面  
 A2 = 双面  
 OT = 其他  
**载体**  
 FG = 玻璃纤维  
 RC = 胶布  
 CB = 组合  
 OT = 其他  
**Spec 05 = 特别产品编码**  
**Thickness (mil)**  
 00 = 定制厚度  
 40 = 40mil  
**81 = 8100 系列**  
**E-Fill = E-Fill 导热填充垫**

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